

Docket No. N1085-00040
Inventor: Ming-Shuh Liang et al.
"A Method Of Providing Via In A Multilayer Semiconductor Device
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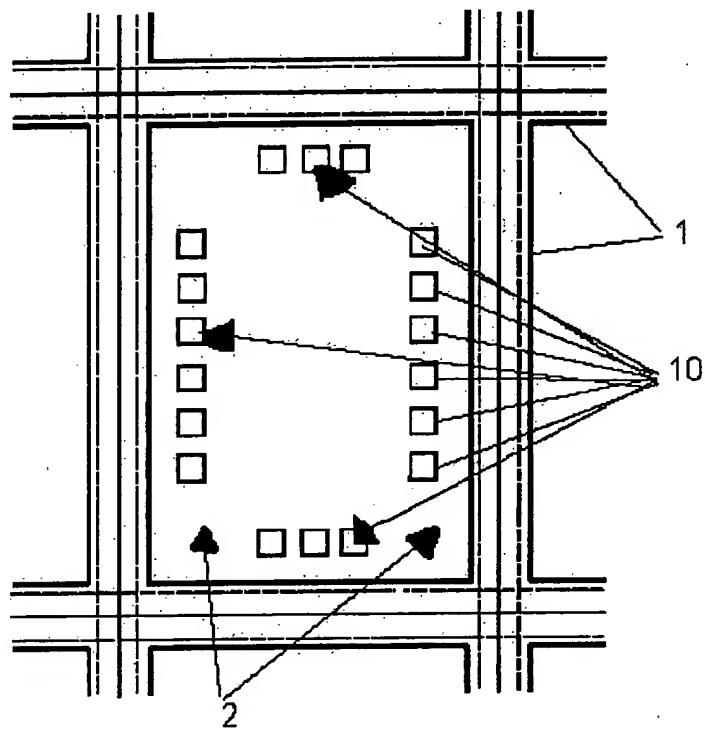


FIG. 1 (PRIOR ART)

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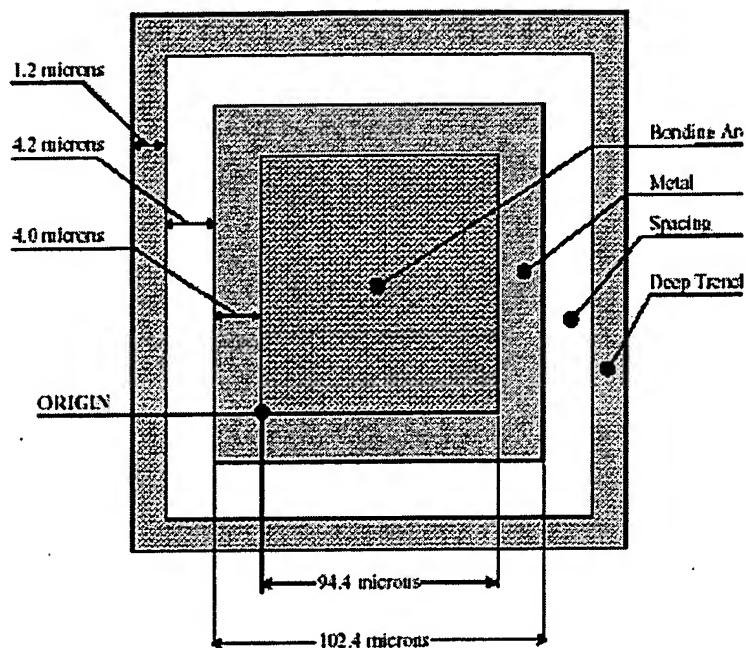


FIG. 2a (PRIOR ART)

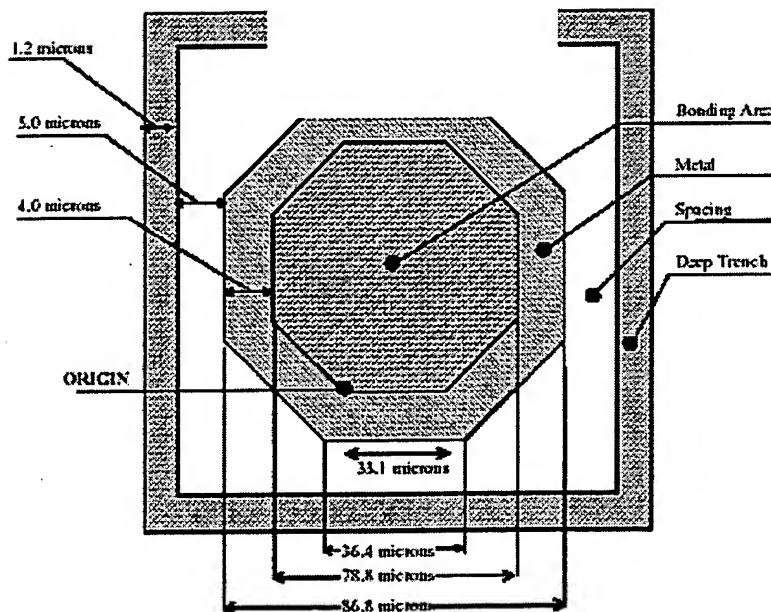


FIG. 2b (PRIOR ART)

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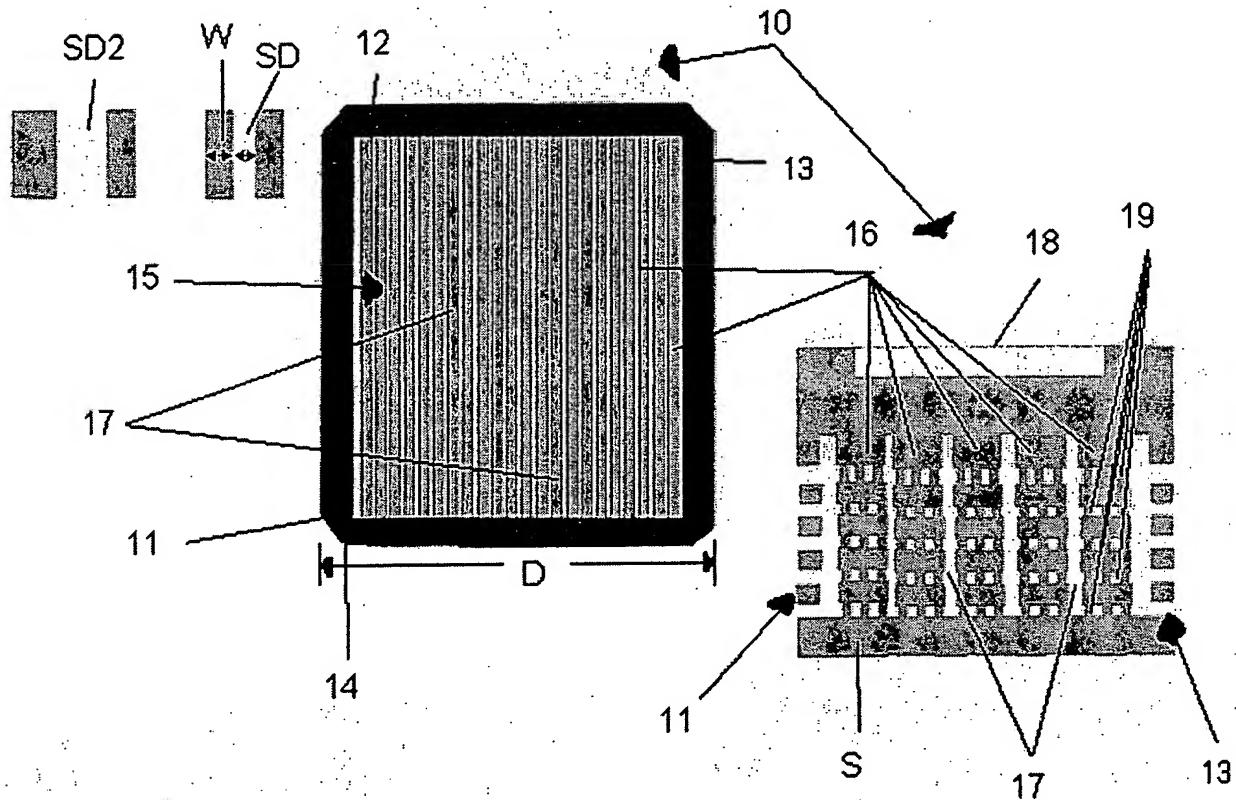


FIG. 3a

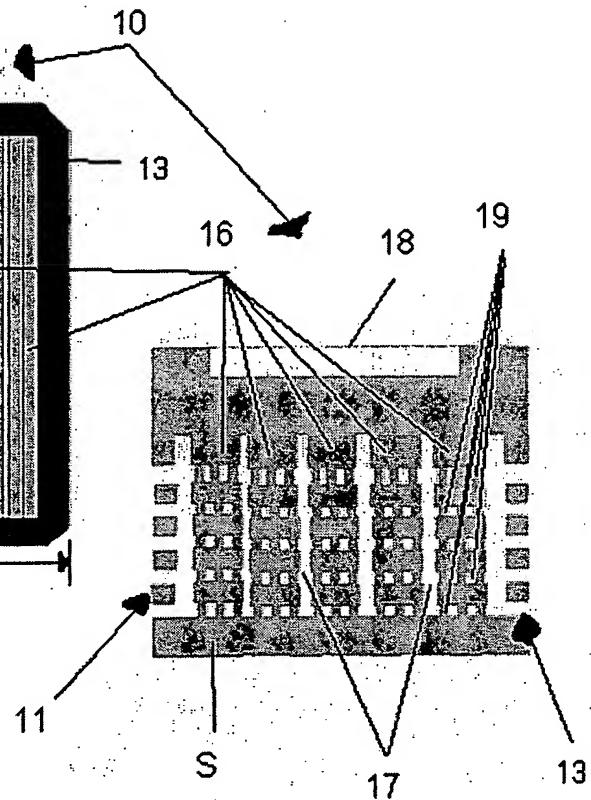


FIG. 3b

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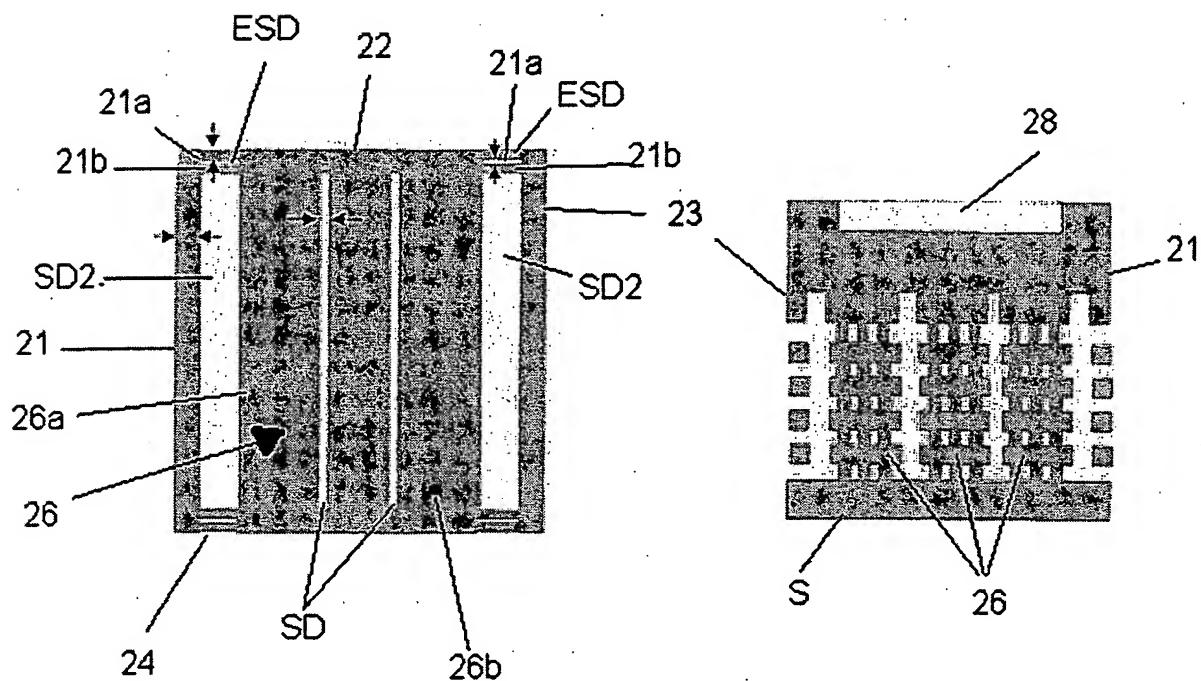


FIG. 4a

FIG. 4b

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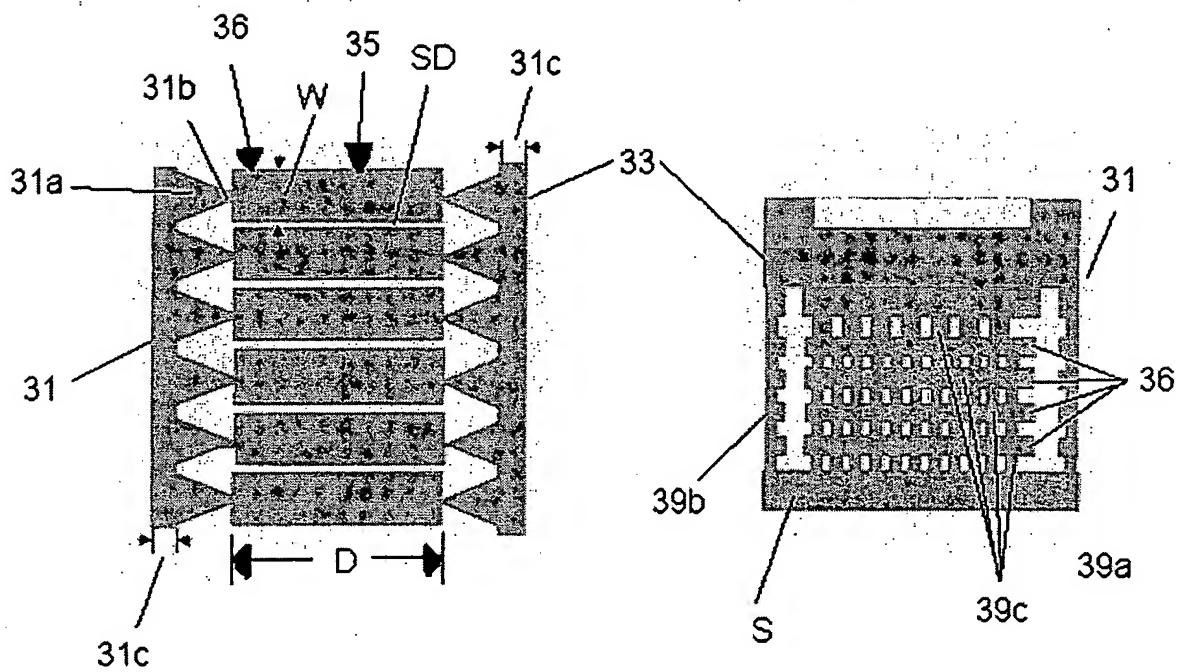


FIG. 5a

FIG. 5b

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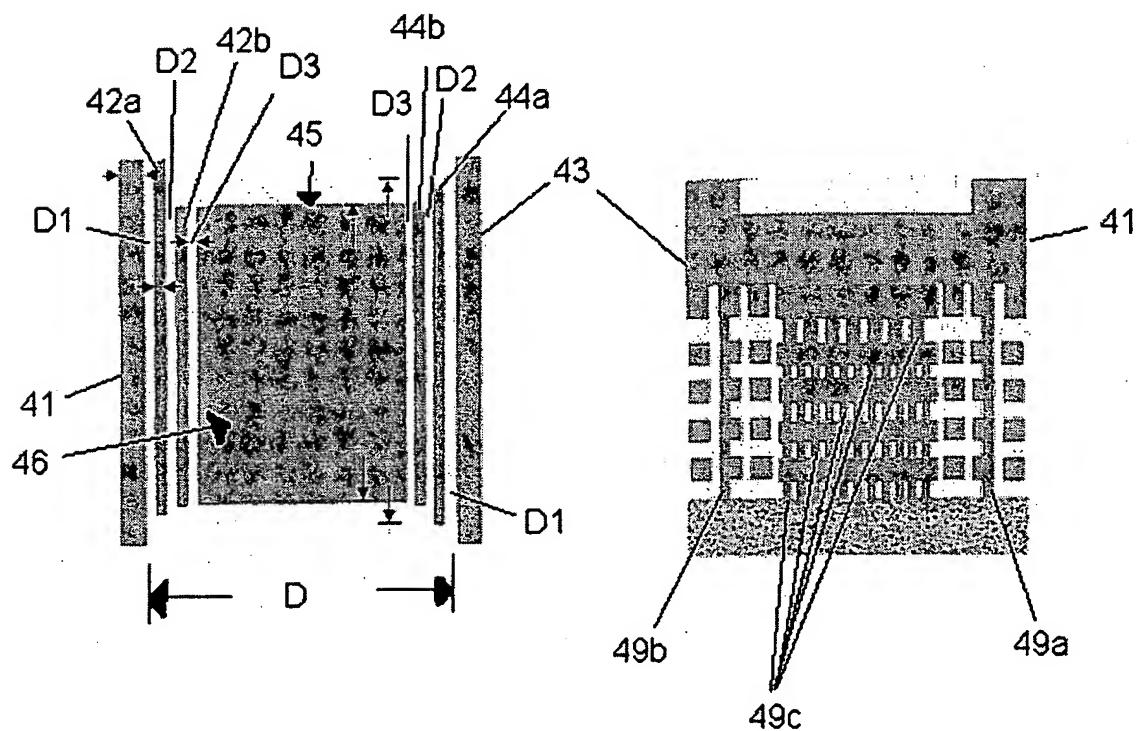


FIG. 6a

FIG. 6b